

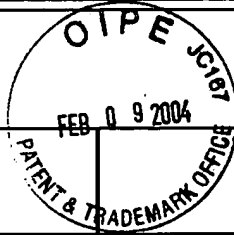
**Change Of Attorney Or Agent's Address In Application
(37 CFR 1.8(a))**

Docket No.
END920030014US1

In Re Application Of: **R. J. Stutzman et al.**

Serial No.
10/634,554

Filing Date
08/05/2003



Examiner
N/A

Group Art Unit
2835

Invention: **FLIP CHIP PACKAGE WITH HEAT SPREADER ALLOWING MULTIPLE HEAT SINK
ATTACHMENT**

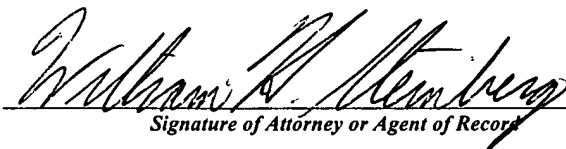
TO THE COMMISSIONER FOR PATENTS

Please send all correspondence for this application to:

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Greenfield Center, NY 12833**

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John A. Jordan, (518) 587-1902


Signature of Attorney or Agent of Record

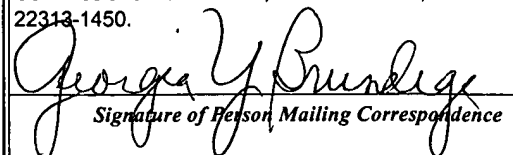
Dated:

2/4/04

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Registration Number & Address of Attorney or Agent of Record

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